1200 V SiC MPS™ Diode



Silicon Carbide Schottky Diode

V_{RRM}	=	1200 V
I _{F (Tc = 135°C)}	=	46 A
\mathbf{Q}_{C}	=	66 nC

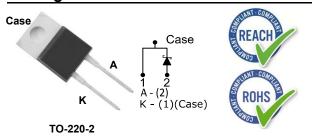
Features

- High Avalanche (UIS) Capability
- Enhanced Surge Current Capability
- Superior Figure of Merit Q_C/I_F
- Low Thermal Resistance
- 175 °C Maximum Operating Temperature
- Temperature Independent Switching Behavior
- Positive Temperature Coefficient of V_F
- Extremely Fast Switching Speeds

Advantages

- Low Standby Power Losses
- Improved Circuit Efficiency (Lower Overall Cost)
- Low Switching Losses
- Ease of Paralleling without Thermal Runaway
- Smaller Heat Sink Requirements
- Low Reverse Recovery Current
- Low Device Capacitance
- Low Reverse Leakage Current

Package



Applications

- Boost Diode in Power Factor Correction (PFC)
- Switched Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Motor Drives
- Freewheeling / Anti-parallel Diode in Inverters
- Solar Inverters
- Electric Vehicles (EV) & Charging Stations
- Induction Heating & Welding

Absolute Maximum Ratings (At T_C = 25 °C Unless Otherwise Stated)

Parameter	Symbol	Conditions	Values	Unit	
Repetitive Peak Reverse Voltage	V_{RRM}		1200	V	
		T _C = 25 °C, D = 1	94		
Continuous Forward Current	I_{F}	$T_C = 135 ^{\circ}C, D = 1$	46	Α	
		$T_C = 165 ^{\circ}C, D = 1$	20		
Non-Repetitive Peak Forward Surge Current, Half Sine Wave	1	$T_C = 25 ^{\circ}\text{C}, t_P = 10 \text{ms}$	120	А	
	I _{F,SM}	T_C = 150 °C, t_P = 10 ms	96		
Repetitive Peak Forward Surge Current, Half Sine Wave	$I_{F,RM}$	T_C = 25 °C, t_P = 10 ms	82	А	
		T_C = 150 °C, t_P = 10 ms	55		
Non-Repetitive Peak Forward Surge Current	I _{F,max}	T _C = 25 °C, t _P = 10 μs	1100	А	
i ² t Value	∫i² dt	T_C = 25 °C, t_P = 10 ms	72	A ² s	
Non-Repetitive Avalanche Energy	E _{AS}	L = 1 mH, I _{AS} = 20 A	220	mJ	
Diode Ruggedness	dV/dt	V _R = 0 ~ 960 V	100	V/ns	
Power Dissipation	P _{tot}	T _C = 25 °C	597	W	
Operating and Storage Temperature	T_j , T_stg		-55 to 175	°C	

1200 V SiC MPS™ Diode



Electrical Characteristics

Power star	Symbol	Canditions		Values		1114	
Parameter Symbol		Conditions		Min.	Тур.	Max.	Unit
Di- d- F		I _F = 20.0 A, T _j = 25 °C			1.5	1.8	V
Diode Forward Voltage V_F $I_F = I_F = $	$I_F = 20.0 A, T_j =$	$I_F = 20.0 \text{ A}, T_j = 175 ^{\circ}\text{C}$		2	2.4		
Reverse Current I _R	,	V _R = 1200 V, T _j	= 25 °C		1.8	18	
	V_R = 1200 V, T_j = 175 °C			5.4	64.8	μA	
T. I. I.O	0		V _R = 400 V		54		
Total Capacitive Charge	Q_{C}		$V_R = 800 \text{ V}$		79		nC
Switching Time t _s	- $dI_F/dt = 200 \text{ A/µs}$ $T_j = 175 ^{\circ}\text{C}$ $V_R = 400 \text{ V}$		- 10				
	$V_{R} = 80$	V _R = 800 V		< 10		ns	
Total Capacitance C	V _R = 1 V, f = 1 MHz, T _j = 25 °C			1298	8		
	C	V _R = 800 V, f = 1 MH	Hz, T _j = 25 °C		83		pF

Thermal / Mechanical Characteristics

Thermal Resistance, Junction - Case	R _{thJC}	0.22	°C/W
Weight	W_{T}	2	g
Mounting Torque	T _M	0.8	Nm

1200 V SiC MPS™ Diode



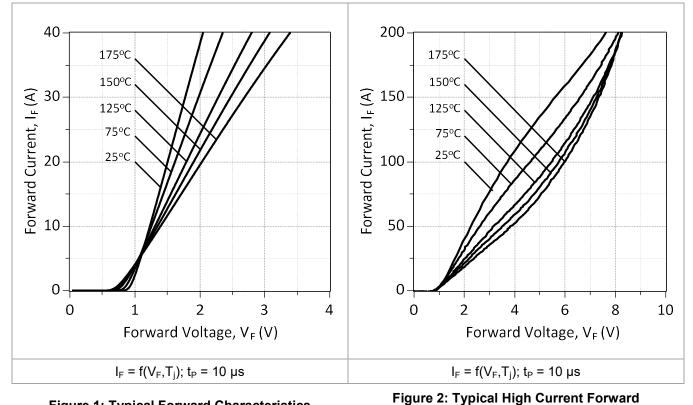


Figure 1: Typical Forward Characteristics

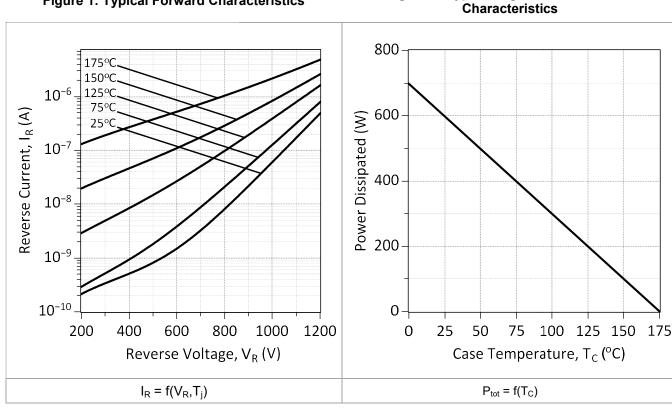


Figure 3: Typical Reverse Characteristics

Figure 4: Power Derating Curve

1200 V SiC MPS™ Diode



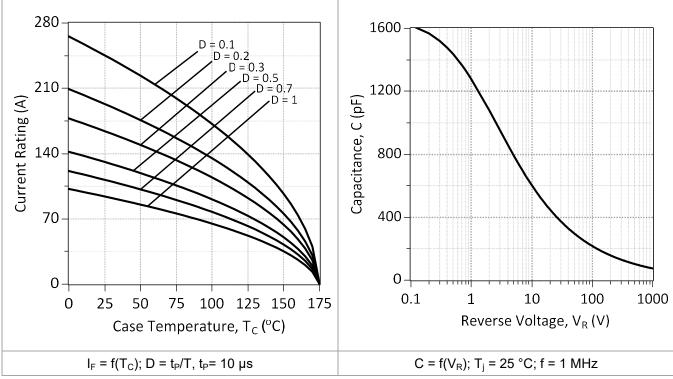


Figure 5: Current Derating Curves(T_j = 206 °C)

90 60 Capacitive Charge, Q_{c} (nC) gStored Energy, $\mathsf{E}_\mathsf{C}\left(\mathsf{\mu}\mathsf{J}\right)$ 40 20 0 0 0 200 400 600 800 1000 1200 0 200 600 800 1000 1200 Reverse Voltage, V_R (V) Reverse Voltage, V_R (V) $Q_c = f(V_R); T_j = 25 \text{ °C}; f = 1 \text{ MHz}$ $E_C = f(V_R); T_j = 25 \, ^{\circ}C; f = 1 \, MHz$

Figure 7: Typical Capacitive Charge vs Reverse Voltage Characteristics

Figure 8: Typical Capacitive Energy vs Reverse Voltage Characteristics

Figure 6: Typical Junction Capacitance vs Reverse Voltage Characteristics



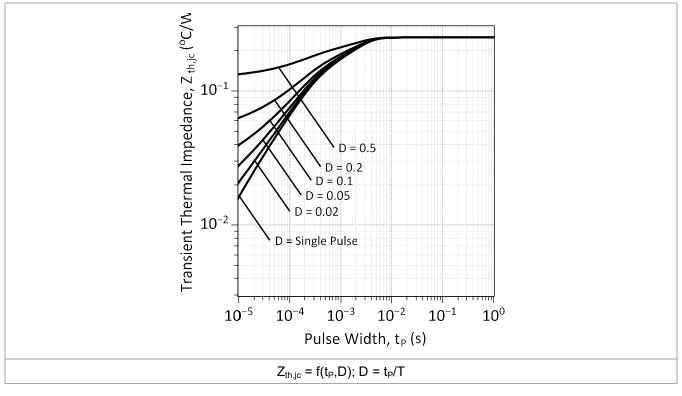


Figure 9: Transient Thermal Impedance

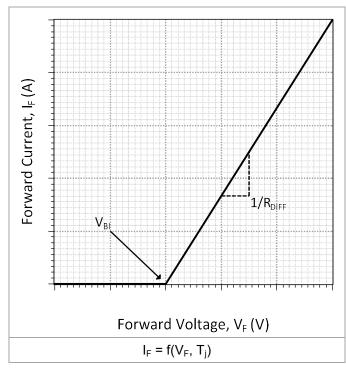


Figure 10: Forward Curve Model

$$I_F = (V_F - V_{BI})/R_{DIFF}(A)$$

Built-In Voltage (V_{BI}):

$$V_{BI}(T_j) = m^*T_j + n (V)$$

 $m = -1.64e-03, n = 1.01$

Differential Resistance (R_{DIFF}):

$$R_{DIFF}(T_j) = a^*T_j^2 + b^*T_j + c (\Omega);$$

 $a = 6.30e-07, b = 1.05e-04, c = 0.0223$

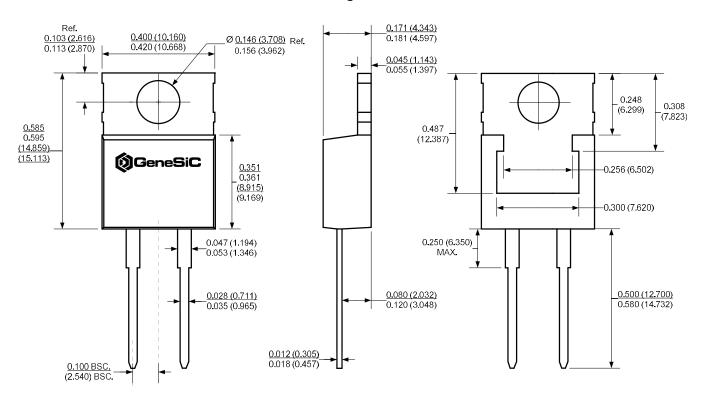
1200 V SiC MPS™ Diode



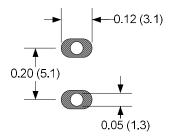
Package Dimensions

TO-220-2L

Package Outline



Recommended Solder Pad Layout



NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

1200 V SiC MPS™ Diode



RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS), as implemented November 15, 2017. RoHS Declarations for this product can be obtained from your GeneSiC representative.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.

GeneSiC disclaims all and any warranty and liability arising out of use or application of any product. No license, express or implied to any intellectual property rights is granted by this document.

Related Links

- Soldering Document: http://www.genesicsemi.com/technical-support/quality /
- Tin-whisker Report: http://www.genesicsemi.com/technical-support/compliance/
- Reliability Report: http://www.genesicsemi.com/technical-support/reliability/